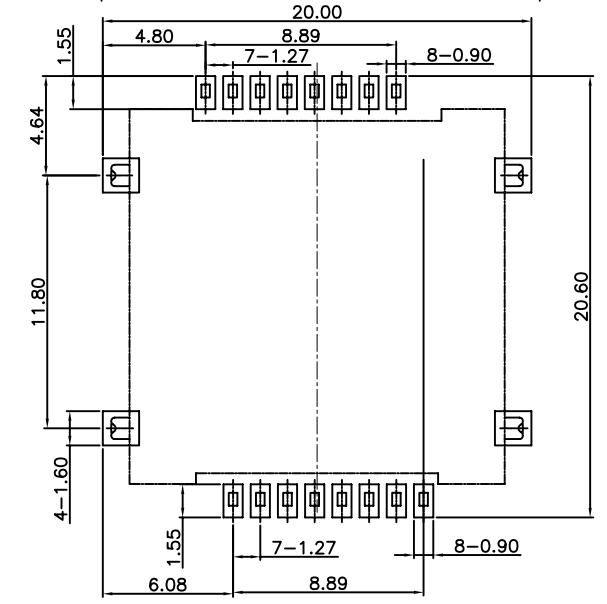
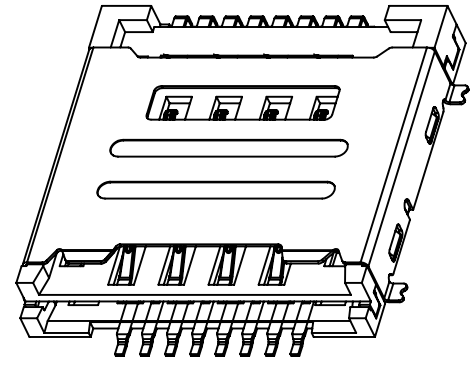
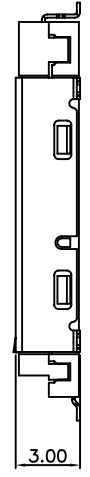
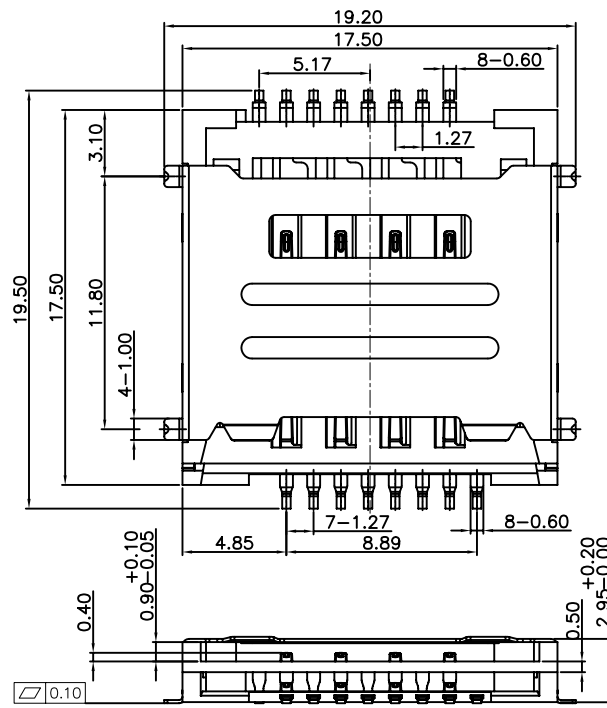
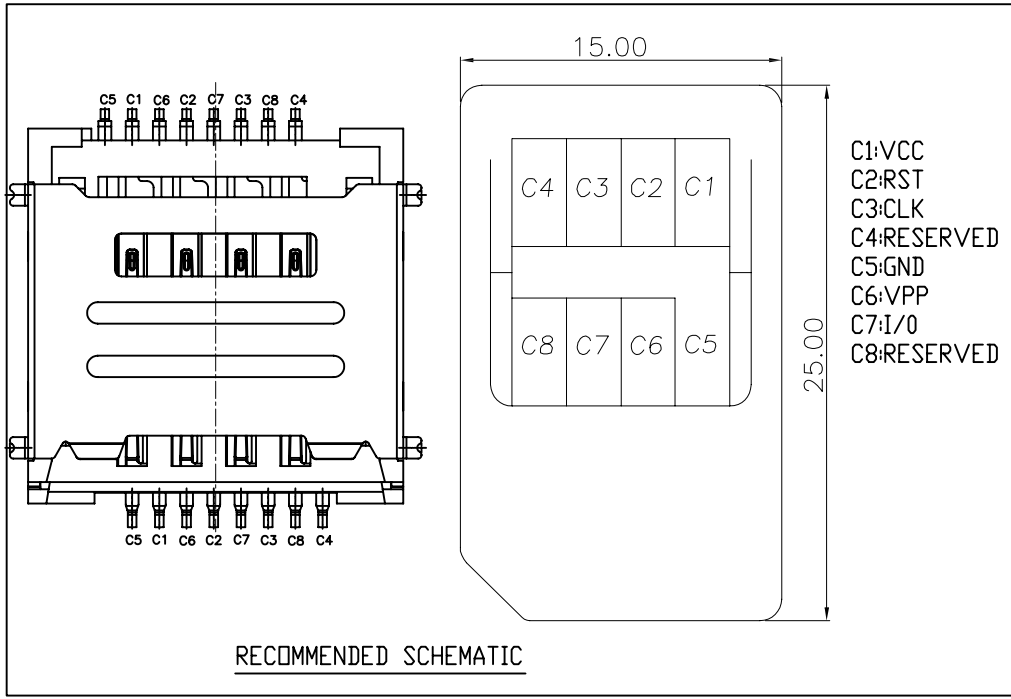


REV	DATE	MODIFICATION	APPROVER
A	20150527	NEW	Jason Lee



RECOMMENDED PC BOARD LAYOUT
TOLFRANCF: +0.05[TOP VIFW]



C1:VCC
C2:RST
C3:CLK
C4:RESERVED
C5:GND
C6:VPP
C7:I/O
C8:RESERVED

NOTE:
1.MATERIAL:
HOUSING:LCP BLACK UL94V-0
CONTACT:COPPER ALLOY(C5210)
SHELL:SUS304
2.PLATED
CONTACT AREA GOLD FLASH PLATED OVER NI
SOLDER TAIL 100u*MIN SN PLATED OVER NI
SHELL:NICKEL 30u*PLATED OVER ALL,GOLD
FLASH PLATED ON SOLDER AREA
3.SPECIFICATION NOTES:
CONTACT RESISTANCE:100 milliohms MAX
CURRENT RATING:0.5A
VOLTAGE RATING:250V
DIELECTRIC WITHSTANDING VOLTAGE:500V AC

GENERAL TOLERANCE		UNITS	NAME:		深圳市爱特姆科技有限公司 SHENZHEN ATOM TECHNOLOGY CO.,LTD.
SELECT	TOL	mm	DUAL SIM CARD 8P		
DN.	1 2 3	MAT'L	PART NO:		TITLE: DUAL SIM CARD 8P SMT H=3.0mm
X.XXX	±0.10±0.05±0.15	FINISH	SI31C-08200		
X.XX	±0.15±0.13±0.25	Q'TY	APPD: Jason		DWG NO. ATOM-A02551
X.X	±0.20±0.25±0.5		CHKD: Vicky		
X.	±0.30±0.36±1.00		DR: JACK		
ANGLE	±2°				
			SCALE	SHEET	REV
			1:1	1/1	A